

Ultra High-Speed Mixed Signal ASICs

Office: (310) 530-9400 Fax: (310) 530-9402 www.adsantec.com

### ASNT6172-KMN Asynchronous FIR Filter and 2x2 Analog Switch

- Dual FIR filter with 9 fully controlled taps for each input analog signal
- Fully differential CML-type analog input interfaces
- Two independent fully differential CML-type analog outputs
- Operates as an analog non-blocking 2x2 switch with a possibility to mix weighted input signals
- High bandwidth DC-28*Gbps* / 20*GHz*
- Total gain up to 6*dB*
- Dual-port 3-wire SPI for tap weight and sign adjustment
- Additional frequency response and gain adjustment through the SPI
- Independent power supplies for analog and digital sections
- Power consumption: <1.25W
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFP 64-pin package





## DESCRIPTION



Fig. 1. Functional Block Diagram

The IC shown in Fig. 1 is a two-channel differential analog 9-tap FIR filter. It receives two high-speed analog signals through its differential input ports d1p/d1n and d2p/d2n. Each channel of FIR has 9 dual taps. Each tap provides two copies of its input signal with controlled polarities. The signals are then processed by analog adders with controlled weight coefficients to perform the pre-emphasis operation. The resulting 4 analog signals (the first and the second signals from the first and the second channels) are sent to the output buffer block that converts them into two output analog signals delivered to linear differential ports q1p/q1n and q2p/q2n. The first output port presents either individual first signal from any channel, or a sum of both first signals. It can be also completely disabled. The second output port presents the second signals from both channels with the same operational modes. Both ports operate in CML-type mode and require external 50*Ohm* terminations.

All chip functions are controlled by internal digital signals delivered through a 3-wire serial-to-parallel interface (SPI) that operates in combination with an internal control block CrlB.



The chip includes a 1-tap replica Rpl that can be independently enabled and used for initial gain calibration as described below.

#### FIR

The FIR consists of two identical channels. At the input of each channel there is a differential transmission line that includes 10 identical sections connected in series to provide ten equal delays. The connection nodes of the sections serve as inputs for 9 taps. The ends of the last section have internal 50*Ohm* terminations to a separate internally generated power supply v2p7. The last section is required for achievement of matching conditions for all taps.

Each tap includes a pair of dual buffers (buf1 and buf2) which allows for generation of two copies of the tap's input signal with polarities individually selected by 1-bit binary signals chX\_inv1 and chX\_inv2, where "0" corresponds to a direct output signal and "1" corresponds to an inverted output signal. Dual buffers in each tap can be individually disabled by special 1-bit binary signals chX\_off1="0" or chX\_off2="0". The buffers of different taps have slightly different gains and internal peaking in order to compensate for transmission line losses.

The 9 pairs of delayed copies of the differential input signal with set polarities are then processed by two 2-stage adders in order to create two linear sums of weighted tap signals. The first stage of each adder consists of three 3-to-1 adders and combines 9 input signals into 3 intermediate signals. The second stage combines those intermediate signals into 1 output signal. Identical 3-to-1 analog adders with digital controls of each input's weight are used in both stages. The control circuitry of the 3-to-1 adder is designed in such a way that the combined weight of all 3 inputs does not exceed the maximum weight of one tap. The control circuitry receives three 6-bit binary signals: the first weight chX\_gncYZ1, the second weight chX\_gncYZ2, and the maximum possible weight chX\_gnmxY, and converts them into another three 6-bit binary signals that control the actual weights of all three inputs. Here X is the channel number 1 or 2; Z is the 2-stage adder number 1 or 2; and Y is the 3-to-1 adder number 1, 2, 3, or 0, where the adders 1, 2, and 3 represent the first stage and the adder 0 represents the second stage. The corresponding algorithm is detailed in Table 1.

Input number	<b>Control signal</b>	Formula	Condition
1	chX_crlYZ1	chX_gncYZ1	if $chX_gncYZ1 \le chX_gnmxY$
		chX_gnmxY	if chX_gncYZ1> chX_gnmxY
2	chX_crlYZ2	chX_gncYZ2	if R1=(chX_gnmxY- chX_gncYZ1)>0 and
			ichX_gncYZ2≤R1
		R1	if R1>0 and chX_gncYZ2>R1
		0	if R1 ≤0
3	chX_crlYZ3	R1-chX_gncYZ2	if R1>0 and R2=R1-chX_gncYZ2>0
		0	if R1≤0 or R2≤0

Table 1.	Wight Contro	ol Algorithm
1 0000 1.		01111501111111

The maximum weight can be adjusted depending on the fabrication process corner. The required value of the maximum weight is defined during initial calibration. The calibration is performed using a replica block Rpl that is described below.



Each tap can be enabled/disabled and its weight and polarity are defined by internal binary signals set through SPI that is also described below.

#### ОВ

The output buffer (OB) takes two pairs of analog signals from the two FIR channels (ch1\_out1, ch1\_out2, ch2\_out1, and ch2\_out2) and delivers them to the two output ports q1p/q1n and q2p/q2n as defined by 2-bit binary control signals obcrl1<1:0> and obcrl2<1:0> according to Table 2. Here X is the channel number 1 or 2.

obcrlX<1>	obcrlX<0>	qX
0	0	Output disabled
0	1	ch1_outX
1	0	ch2_outX
1	1	$0.5*(ch1_outX)+0.5*(ch2_outX)$

Table 2. Output Buffer Operational Modes

#### CrIB

The control block (CrlB) converts binary signals from SPI into analog voltages that control internal peaking and linearity parameters of FIR channels. The peaking can be adjusted by 6-bit binary signals  $chX\_ief<5:0>$  where higher values corresponding to higher bandwidth with associated high-frequency peaking of the channel's frequency response. The linearity can be adjusted by 6-bit binary signals  $chX\_icsc<5:0>$  where higher values correspond to higher linearity at low weights.

#### Rpl

The tap replica (Rpl) is used for initial tap gain calibration to ensure the optimal maximum data signal swing at the outputs of the first stages of both adders.

Rpl is an exact copy of Tap1. In the optimal state, it should generate a predefined DC voltage difference between its outputs **qrepp** and **qrepn**. This difference should be adjusted to the value specified in ELECTRICAL CHARACTERISTICS using the 6-bit binary signal ch1\_gnmx1. Rpl is used for initial calibration only and can be completely disabled by the binary signal onrep="0".

### SPI

The 3-wire SPI operates in slave mode and accepts three CMOS signals: **3wenin (SSn)**, **3wcin (SCLK)**, and **3wdin (MOSI)** as described in ELECTRICAL CHARACTERISTICS. Additional CMOS data output **3wdout (MISO)** is provided for control purposes.

SPI converts 40 input serial bytes into 115 parallel binary control signals. The SPI byte description is presented in Table 3.



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SPI	Byte	Bit Number					
Section	Number	7 (MSB for Left)	6	5 4	3 2	1	0 (MSB for Right)
Left	1	onrep X			•	ch1_gnmx1	
	2	obcrl1				ch1_gnm	x0
	3	$ch1_off1(1)$	$ch1_inv1(1)$			ch1_gnc1	.11
	4	$ch1_off1(2)$	ch1_inv1(2)			ch1_gnc	112
	5	$ch1_off1(3)$	$ch1_inv1(3)$			ch1_gnc1	21
	6	$ch1_off1(4)$	ch1_inv1(4)			ch1_gnc	122
	7	$ch1_off1(5)$	$ch1_inv1(5)$			ch1_gnc2	211
	8	ch1_off1(6)	ch1_inv1(6)			ch1_gnc2	212
	9	ch1_off1(7)	ch1_inv1(7)			ch1_gnc2	221
	10	ch1_off1(8)	ch1_inv1(8)			ch1_gnc2	222
	11	ch1_off1(9)	ch1_inv1(9)			ch1_gnc3	311
	12	$ch1_off2(1)$	$ch1_iv2(1)$			ch1_gnc.	312
	13	$ch1_off2(2)$	$ch1_inv2(2)$			ch1_gnc3	321
	14	$ch1_off2(3)$	$ch1_iv2(3)$			ch1_gnc.	322
	15	$ch1_off2(4)$	$ch1_iv2(4)$			ch1_gnc(	)11
	16	$ch1_off2(5)$	$ch1_iv2(5)$			ch1_gnc	012
	17	ch1_off2(6)	ch1_inv2(6)			ch1_gnc(	021
	18	ch1_off2(7)	ch1_inv2(7)			ch1_gnc	)22
	19	ch1_off2(8)	ch1_inv2(8)			ch1_ef1 (D	AC)
	20	ch1_off2(9)	ch1_inv2(9)			ch1_csc (D	AC)
	21	Х	Х			ch1_ef2 (D	AC)
Right	22	ch2_ef2 (DA	C) (reversed bit	order)		Х	Х
	23	ch2_csc (DA	C) (reversed bit	order)		ch2_inv2(9)	ch2_off2(9)
	24	ch2_ef1 (DA	C) (reversed bit	order)		ch2_inv2(8)	ch2_off2(8)
	25	ch2_gnc022	2 (reversed bit of	order)		ch2_inv2(7)	ch2_off2(7)
	26	ch2_gnc021 (reversed bit order)				ch2_inv2(6)	ch2_off2(6)
	27	ch2_ gnc012 (reversed bit order)				$ch2_inv2(5)$	ch2_off2(5)
	28	ch2_gnc011	(reversed bit c	order)		$ch2_inv2(4)$	ch2_off2(4)
	29	ch2_gnc322	2 (reversed bit o	order)		$ch2_inv2(3)$	ch2_off2(3)
	30	ch2_gnc321	(reversed bit c	order)		$ch2_inv2(2)$	ch2_off2(2)
	31	ch2_gnc312	2 (reversed bit of	order)		$ch2_inv2(1)$	$ch2_off2(1)$
	32	ch2_gnc311	(reversed bit c	order)		$ch2_inv1(9)$	ch2_off1(9)
	33	ch2_ gnc222	2 (reversed bit of	order)		ch2_inv1(8)	ch2_off1(8)
	34	ch2_gnc221	order)		$ch2_inv1(7)$	ch2_off1(7)	
	35	ch2_gnc212	order)		ch2_inv1(6)	ch2_off1(6)	
	36	ch2_gnc211	order)		ch2_inv1(5)	ch2_off1(5)	
	37	ch2_ gnc122	2 (reversed bit of	order)		ch2_inv1(4)	ch2_off1(4)
	38	ch2_gnc121	(reversed bit o	order)		ch2_inv1(3)	ch2_off1(3)
	39	ch2_gnc112	2 (reversed bit o	order)		$ch2_inv1(2)$	ch2_off1(2)
	40	ch2_gnc111	(reversed bit o	order)		$ch2_inv1(1)$	ch2_off1(1)
	41	ch2_gnmx0	(reversed bit o	rder)		obcrl2 (r	eversed bit order)
	42	ch2 gnmx1	(reversed bit o	rder)		X	X

Table 3. SPI Control Bytes

The bytes are delivered starting from 1 to 40 and bits within a byte are delivered starting from MSB. Bit#7 is the MSB of a byte as shown in Fig. 2. Internal registers are updated at a rising edge of **3wenin**.

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3wcin	
3wenin	
Sample	
Latch	
3wdin X 7 6 5 4 3 2 1 0 Byte 1	7 6 5 4 3 2 1 0 X Byte N

Fig. 2. SPI Operation

### **POWER SUPPLY CONFIGURATION**

The IC requires three positive external power supplies. The first supply v2p9 is used for the data output terminations and to power all high-speed circuitry and reference sources. The second supply v4p0 powers the internal analog adder circuitry. The digital supply v1p2 is used for the internal CMOS circuits of the SPI.

All supplies are positive in relation to the internal common node vee=0.0V.

### **ABSOLUTE MAXIMUM RATINGS**

Caution: Exceeding the absolute maximum ratings may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Parameter	Min	Max	Units
Supply Voltage (v4p0)		+4.4	V
Supply Voltage (v2p9, v2p7)		+3.6	V
Supply Voltage (v1p2)		+1.5	V
RF Input Voltage Swing (SE)		0.5	V
Case Temperature		+90	°С
Storage Temperature	-40	+100	°С
Operational Humidity	10	98	%
Storage Humidity	10	98	%

Table 4. Absolute	Maximum	Ratings
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# **TERMINAL FUNCTIONS**

TERMINAL		ERMINAL	Description		
Name	No.	Туре	Description		
	High-Speed I/Os				
d1p	53	CML-type input	Differential high-speed data inputs with internal SE 500hm		
d1n	60		terminations to v2p9		
d2p	28	CML-type input			
d2n	21				
q1p	12	CML-type output	Differential high-speed data outputs with internal SE 500hm		
q1n	5		terminations to v2p9; require external SE 500hm terminations		
q2p	37	CML-type output	to v2p9.		
q2n	44				
			Low-Speed I/Os		
3wenin	26	1.2V CMOS input	Enable input signal SSn for 3-wire interface		
3wcin	25		Clock input signal SCLK for 3-wire interface		
3wdin	24		Data input signal MOSI for 3-wire interface		
3wdo	23	1.2V CMOS output	Data output signal MISO for 3-wire interface		
	Analog Control Voltages				
v2p7	9	Internal voltage	Internal voltage source of v2p9-0.2V		
		generator output			
		Analog Contr	rol Nodes (for DMM measurements only!)		
qrepp	62	Analog DC output	Replica differential data outputs		
grepn	3	_			

	Supply And Termination Voltages			
Name	Description	Pin Number		
vee	External ground	2, 4, 6, 11, 13, 15, 18, 20, 22, 27, 29, 31,		
		34, 36, 38, 43, 45, 47, 50, 52, 54, 59, 61,		
		63		
v2p9	Positive power supply	7, 10, 17, 32, 33, 48, 49, 64		
v4p0	Positive power supply	14, 19, 30, 35, 39, 42, 46, 51		
v1p2	Positive power supply	1, 16		
nc	not connected pins	8, 40, 41, 55, 56, 57, 58		



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# **ELECTRICAL CHARACTERISTICS**

PARAMETER	MIN TYP	MAX	UNIT	COMMENTS			
General Parameters							
v2p9	2.9		V	Analog supply			
v4p0	4.0		V	Analog supply			
vdd	1.2		V	CMOS digital supply			
vee	0.0		V	External ground			
In Only	400		mA	All taps enabled, maximum peaking			
IV2p9	175		mA	3 equivalent taps in each channel			
Iv4p0	180	215	mA	Depending on bandwidth control			
				settings			
Power consumption	1.25	2.1	W				
Junction temperature	-25 50	125	°C				
		FIR Para	ameters				
No. of Taps	2x2x9						
Delay between Taps	13.5		ps				
Voltage gain	6		dB	From chip input to chip output			
	High Speed Input Data (d1p/d1n, d2p/d2n)						
Data Rate	DC	28	Gb/s				
Swing in linear mode	110		mV	Differential or SE, p-p			
S11	TBD		dB				
CM Voltage Level	v2p7-0.2	2	V	Must match for both inputs			
	Analog Out	put Data	(q1p/q1n	, q2p/q2n)			
Bandwidth	DC	20	GHz				
Swing	220		mV	At each SE output			
S22	TBD		dB				
CM Voltage Level	2.5		V				
	D	C Contro	l Voltages	5			
qrp-qrn	grp-grn 220		mV	With optimal ch1_gnmx1			
	3-V	Vire Inter	rface Port	ts			
Clock frequency		6	MHz				
Low logic level	0		V				
High logic level	High logic level 1.2		V				

## **PACKAGE INFORMATION**

The chip die is housed in a custom, 64-pin CQFP package. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the **vee** plain, which is ground for a positive supply.

The part's identification label is ASNT6172-KMN. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part



version while the 3 digits after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with Commission Delegated Directive (EU) 2015/863 of 4 June 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council as regards the list of restricted substances (Text with EEA relevance) on the restriction of the use of certain hazardous substances in electrical and electronics equipment (RoHS Directive) in accordance with the definitions set forth in the directives for all ten substances.

Revision	Date	Changes	
1.2.2	11-2020	Corrected connection to the heat slug	
1.1.2	10-2020	Corrected Terminal Functions table (q2p pin)	
		Updated packaging information	
1.0.2	02-2020	First release	
0.1.2	02-2020	Corrected block diagram	
		Corrected package information	
0.0.2	08-2019	Changed header	
		Corrected SPI byte table	
0.0.1	09-2017	Preliminary release	

### **REVISION HISTORY**